



Material Content Data Sheet



Sales Product Name		IPAN50R500CE		Issued		1. August 2018		
MA#		MA002187796						
Package		PG-TO220-3-319		Weight*		2203.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.939	0.13	0.13	1334	1334
leadframe	inorganic material	phosphorus	7723-14-0	0.345	0.02		156	
	non noble metal	iron	7439-89-6	1.149	0.05		521	
	non noble metal	copper	7440-50-8	1147.227	52.08	52.15	520745	521422
	non noble metal	aluminium	7429-90-5	0.809	0.04	0.04	367	367
wire	non noble metal	aluminium	7429-90-5	0.809	0.04	0.04	367	367
encapsulation	organic material	carbon black	1333-86-4	10.399	0.47		4720	
	plastics	epoxy resin	-	166.835	7.57		75729	
	inorganic material	silicondioxide	60676-86-0	864.257	39.23	47.27	392300	472749
leadfinish	non noble metal	tin	7440-31-5	7.148	0.32	0.32	3245	3245
solder	non noble metal	antimony	7440-36-0	0.194	0.01		88	
	noble metal	silver	7440-22-4	0.486	0.02		221	
	non noble metal	tin	7440-31-5	1.264	0.06	0.09	574	883
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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